



ALPHA & OMEGA
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AOS Semiconductor Product Reliability Report

AOW480, rev A

Plastic Encapsulated Device

ALPHA & OMEGA Semiconductor, Inc

www.aosmd.com



This AOS product reliability report summarizes the qualification result for AOW480. Accelerated environmental tests are performed on a specific sample size, and then followed by electrical test at end point. Review of final electrical test result confirms that AOW480 passes AOS quality and reliability requirements. The released product will be categorized by the process family and be monitored on a quarterly basis for continuously improving the product quality.

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I. Product Description:

The AOW480 is fabricated with SDMOS™ trench technology that combines excellent $R_{DS(ON)}$ with low gate charge & low Q_{rr} . The result is outstanding efficiency with controlled switching behavior. This universal technology is well suited for PWM, load switching and general purpose applications.

- RoHS Compliant
- Halogen Free

Details refer to the datasheet.

II. Die / Package Information:

	AOW480
Process	Standard sub-micron Low voltage N channel process
Package Type	3 leads TO262
Lead Frame	Bare Cu
Die Attach	Soft solder
Bond wire	Al wire
Mold Material	Epoxy resin with silica filler
Moisture Level	Up to Level 1 *
Note * based on info provided by assembler and mold compound supplier	

III. Result of Reliability Stress for AOW480

Test Item	Test Condition	Time Point	Lot Attribution	Total Sample size	Number of Failures	Reference Standard
MSL Precondition	168hr 85°c /85%RH +3 cycle reflow @250°c	-	3 lots	627pcs	0	JESD22-A113
HTGB	Temp = 150°c , Vgs=100% of Vgsmax	168hrs 500 hrs 1000 hrs	3 lots (Note A*)	231pcs 77 pcs / lot	0	JESD22-A108
HTRB	Temp = 150°c , Vds=80% of Vdsmax	168hrs 500 hrs 1000 hrs	3 lots (Note A*)	231pcs 77 pcs / lot	0	JESD22-A108
HAST	130 +/- 2°c , 85%RH, 33.3 psi, Vgs = 100% of Vgs max	100 hrs	3 lots (Note A*)	165pcs 55 pcs / lot	0	JESD22-A110
Pressure Pot	121°c , 29.7psi, RH=100%	96 hrs	3 lots (Note A*)	231pcs 77 pcs / lot	0	JESD22-A102
Temperature Cycle	-65°c to 150°c , air to air,	250 / 500 cycles	3 lots (Note A*)	231pcs 77 pcs / lot	0	JESD22-A104

Note A: The reliability data presents total of available generic data up to the published date.

IV. Reliability Evaluation

FIT rate (per billion): 15
MTTF = 7435 years

The presentation of FIT rate for the individual product reliability is restricted by the actual burn-in sample size of the selected product (AOW480). Failure Rate Determination is based on JEDEC Standard JESD 85. FIT means one failure per billion hours.

$$\text{Failure Rate} = \text{Chi}^2 \times 10^9 / [2 (N) (H) (Af)] = 1.83 \times 10^9 / [2 \times 3 \times 2 \times 77 \times 500 \times 258] = 15$$

$$\text{MTTF} = 10^9 / \text{FIT} = 6.51 \times 10^7 \text{hrs} = 7435 \text{ years}$$

Chi² = Chi Squared Distribution, determined by the number of failures and confidence interval

N = Total Number of units from HTRB and HTGB tests

H = Duration of HTRB/HTGB testing

Af = Acceleration Factor from Test to Use Conditions (Ea = 0.7eV and Tuse = 55°C)

Acceleration Factor [**Af**] = $\text{Exp} [Ea / k (1/Tj u - 1/Tj s)]$

Acceleration Factor ratio list:

	55 deg C	70 deg C	85 deg C	100 deg C	115 deg C	130 deg C	150 deg C
Af	258	87	32	13	5.64	2.59	1

Tj s = Stressed junction temperature in degree (Kelvin), K = C+273.16

Tj u = The use junction temperature in degree (Kelvin), K = C+273.16

k = Boltzmann's constant, 8.617164 X 10⁻⁵eV / K